

30V N-Channel Enhancement Mode MOSFET

Description

The UCB3400 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

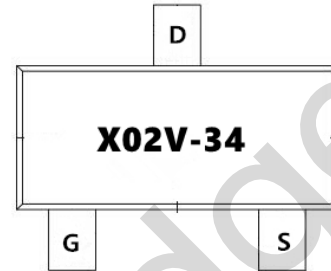
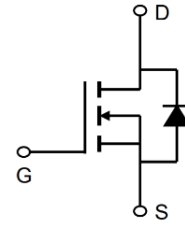
$V_{DS} = 30V$ $I_D = 5.8A$

$R_{DS(ON)} < 35m\Omega$ @ $V_{GS}=4.5V$ (Type: 28m Ω)

Application

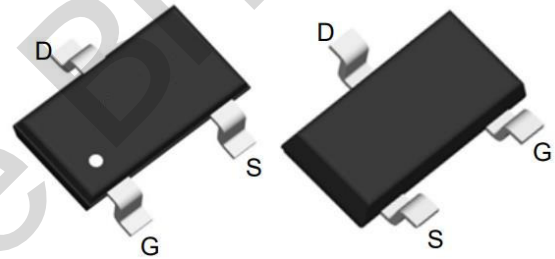
Load switch

Uninterruptible power supply



Top View

Bottom View



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
UCB3400	SOT23-3L	X0V2-34	3000

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	5.8	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	3.1	A
I_{DM}	Pulsed Drain Current ²	16	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ³	1	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	125	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	80	$^\circ\text{C}/\text{W}$

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	32	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.029	---	$V/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=4A$		27	30	$\text{m}\Omega$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=4.5V, I_D=3A$	---	28	35	$\text{m}\Omega$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=2.5V, I_D=2A$	---	38	50	$\text{m}\Omega$
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.5	0.95	1.2	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-2.82	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=24V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=24V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=3A$	---	19	---	S
Rg	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	1.5	3	Ω
Qg	Total Gate Charge (4.5V)	$V_{DS}=15V, V_{GS}=4.5V, I_D=3A$	---	8.34	11.7	nC
Qgs	Gate-Source Charge		---	1.26	1.8	
Qgd	Gate-Drain Charge		---	1.88	2.6	
Td(on)	Turn-On Delay Time	$V_{DD}=15V, V_{GS}=4.5V, R_G=3.3\Omega, I_D=3A$	---	3.2	6.4	ns
Tr	Rise Time		---	41.8	75	
Td(off)	Turn-Off Delay Time		---	21.2	42	
Tf	Fall Time		---	6.4	12.8	
Ciss	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	662	927	pF
Coss	Output Capacitance		---	51.3	72	
Crss	Reverse Transfer Capacitance		---	43.6	61	
IS	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	3.9	A
ISM	Pulsed Source Current ^{2,4}	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	16	A
VSD	Diode Forward Voltage ²		---	---	1.2	V
trr	Reverse Recovery Time	$I_F=3A, dI/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	6.8	---	nS
Qrr	Reverse Recovery Charge		---	2.3	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

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Typical Characteristics

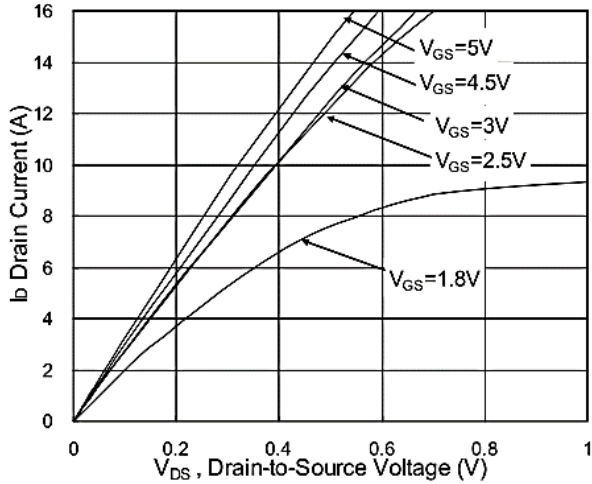


Fig.1 Typical Output Characteristics

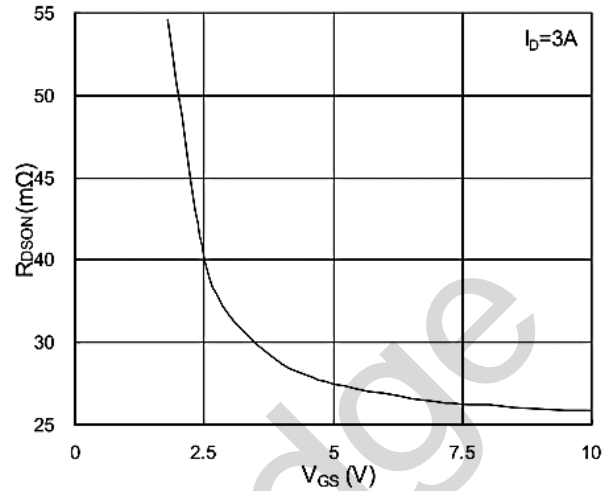


Fig.2 On-Resistance vs G-S Voltage

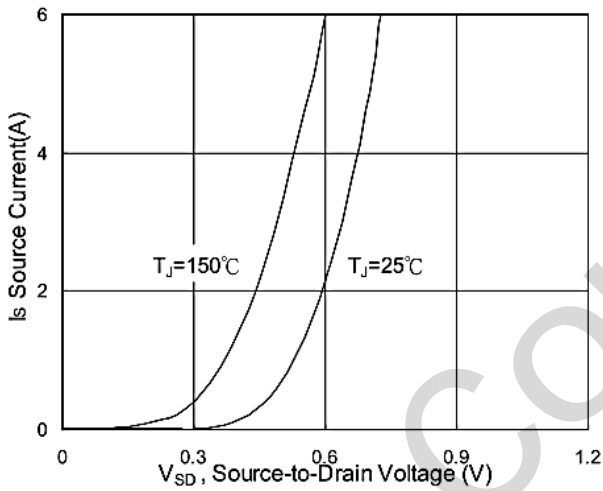


Fig.3 Source Drain Forward Characteristics

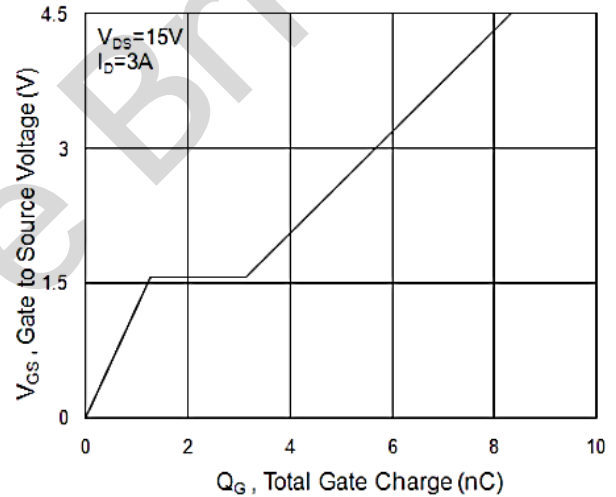


Fig.4 Gate-Charge Characteristics

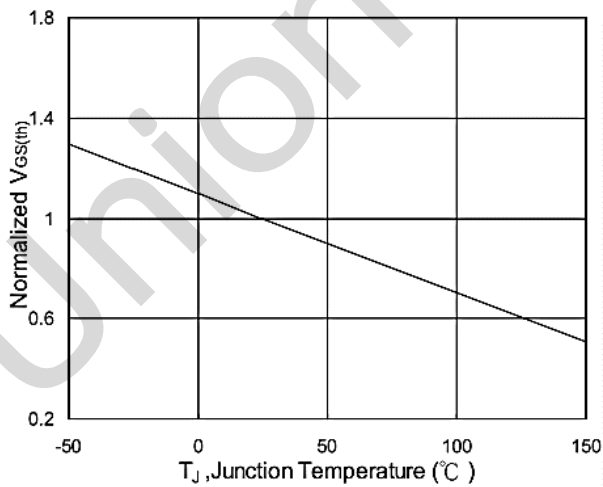


Fig.5 Normalized $V_{GS(th)}$ vs T_J

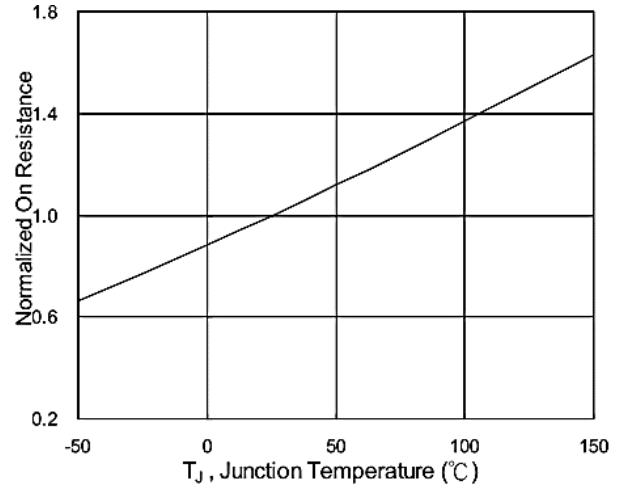


Fig.6 Normalized $R_{DS(on)}$ vs T_J

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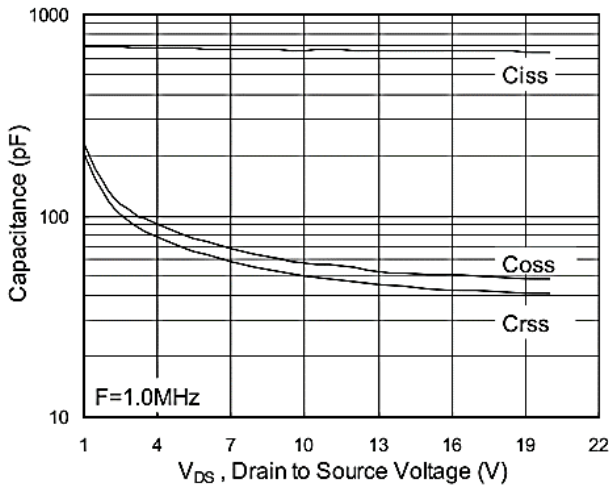


Fig.7 Capacitance

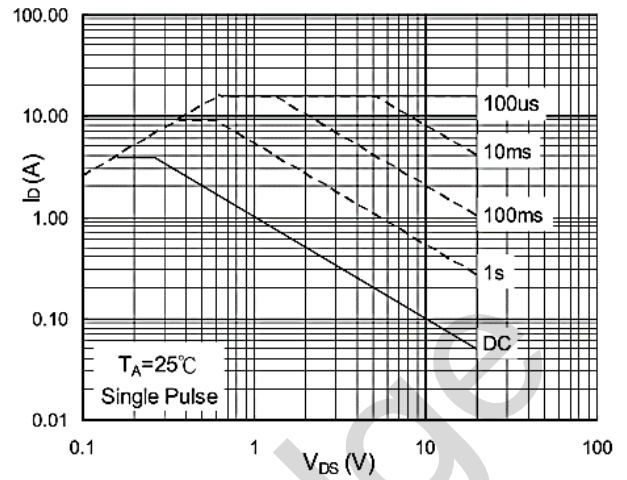


Fig.8 Safe Operating Area

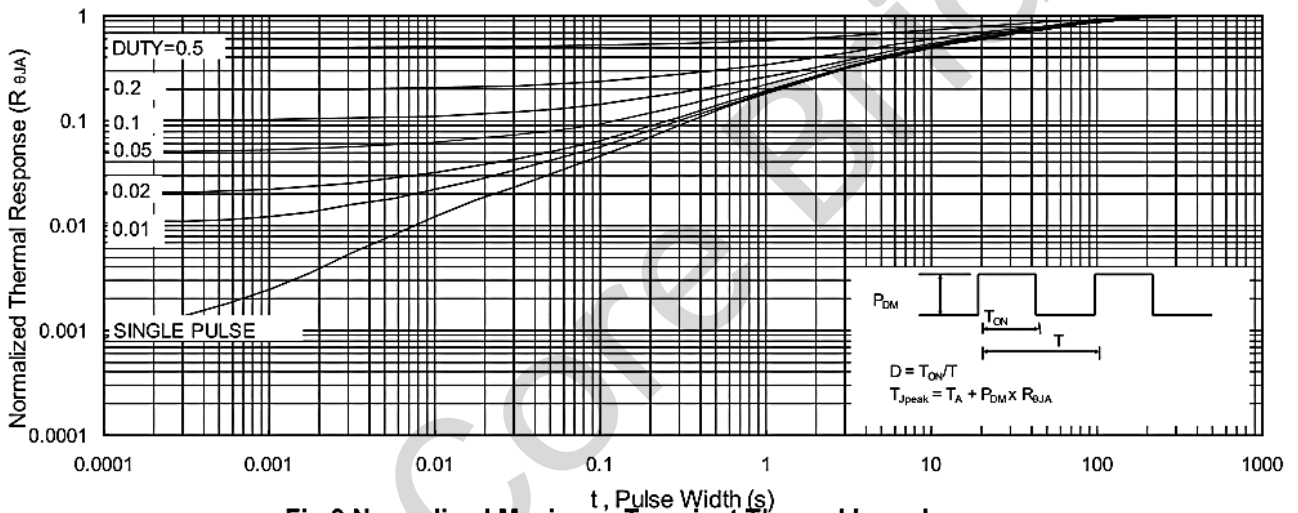


Fig.9 Normalized Maximum Transient Thermal Impedance

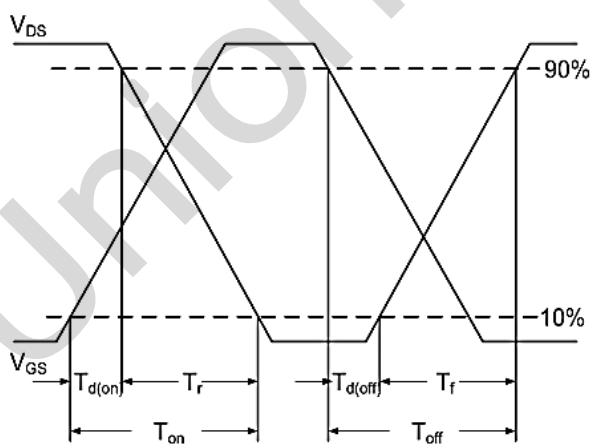


Fig.10 Switching Time Waveform

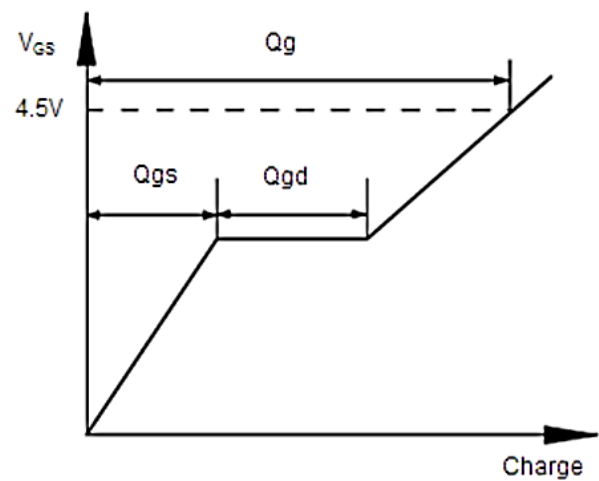
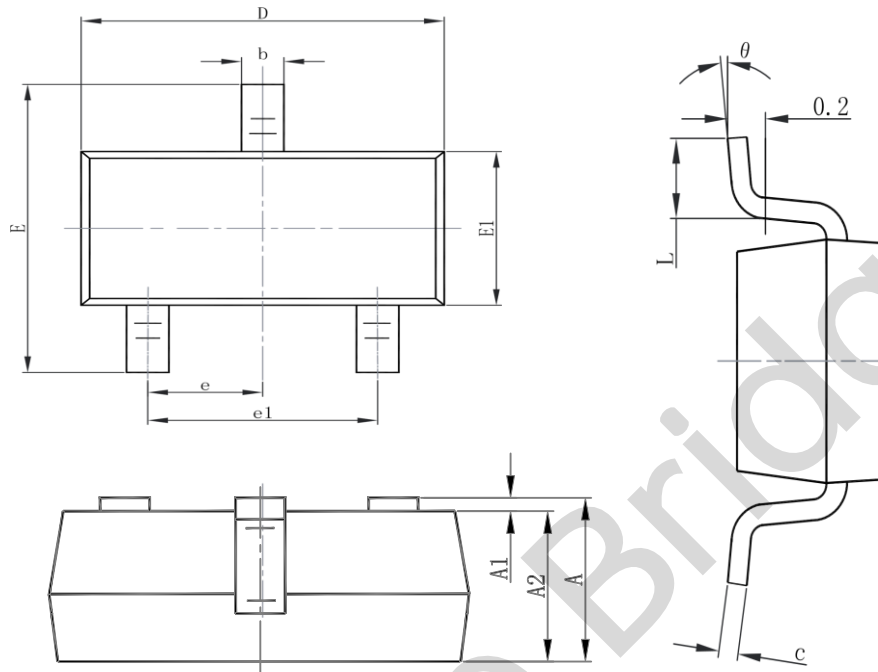


Fig.11 Gate Charge Waveform

Package Mechanical Data-SOT23-3-SLS-Single



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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